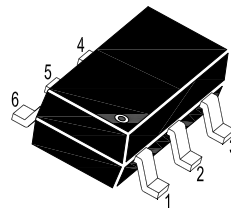
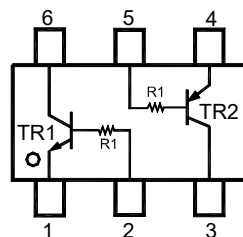


# MMDTX430DW

## Complementary NPN/PNP Silicon Epitaxial Planar Digital Transistor

### Features

- Built-in bias resistors R1
- Simplification of circuit design
- Reduces number of components and board space



TR1: 1. Emitter 2. Base 6. Collector  
TR2: 4. Emitter 5. Base 3. Collector  
SOT-363 Plastic Package

### NPN Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ unless otherwise specified)(TR1)

Parameter	Symbol	Value	Unit
Collector Base Voltage	$V_{\text{CBO}}$	50	V
Collector Emitter Voltage	$V_{\text{CEO}}$	50	V
Emitter Base Voltage	$V_{\text{EBO}}$	5	V
Collector Current	$I_{\text{C}}$	100	mA
Peak Collector Current	$I_{\text{CM}}$	100	mA
Total Power Dissipation <sup>1)</sup>	$P_{\text{D}}$	200	mW
Operating Junction Temperature	$T_{\text{j}}$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{\text{stg}}$	- 55 to + 150	$^\circ\text{C}$

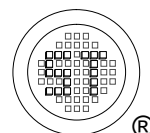
### PNP Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ unless otherwise specified)(TR2)

Parameter	Symbol	Value	Unit
Collector Base Voltage	$-V_{\text{CBO}}$	50	V
Collector Emitter Voltage	$-V_{\text{CEO}}$	50	V
Emitter Base Voltage	$-V_{\text{EBO}}$	5	V
Collector Current	$-I_{\text{C}}$	100	mA
Peak Collector Current	$-I_{\text{CM}}$	100	mA
Total Power Dissipation <sup>1)</sup>	$P_{\text{D}}$	200	mW
Operating Junction Temperature	$T_{\text{j}}$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{\text{stg}}$	- 55 to + 150	$^\circ\text{C}$

### Thermal Characteristics (TR1、TR2)

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient <sup>1)</sup>	$R_{\theta\text{JA}}$	625	$^\circ\text{C/W}$

<sup>1)</sup> Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.



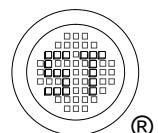
# MMDTX430DW

## NPN Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified (TR1)

Parameter	Symbol	Min.	Typ.	Max.	Unit
DC Current Gain at $V_{CE} = 5\text{ V}$ , $I_C = 1\text{ mA}$	$h_{FE}$	200	-	-	-
Collector Base Cutoff Current at $V_{CB} = 50\text{ V}$	$I_{CBO}$	-	-	100	nA
Collector Emitter Cutoff Current at $V_{CE} = 30\text{ V}$	$I_{CEO}$	-	-	1	$\mu\text{A}$
Emitter Base Cutoff Current at $V_{EB} = 5\text{ V}$	$I_{EBO}$	-	-	100	nA
Collector Base Breakdown Voltage at $I_C = 50\text{ }\mu\text{A}$	$V_{(BR)CBO}$	50	-	-	V
Collector Emitter Breakdown Voltage at $I_C = 1\text{ mA}$	$V_{(BR)CEO}$	50	-	-	V
Emitter Base Breakdown Voltage at $I_E = 50\text{ }\mu\text{A}$	$V_{(BR)EBO}$	5	-	-	V
Collector Emitter Saturation Voltage at $I_C = 5\text{ mA}$ , $I_B = 0.25\text{ mA}$	$V_{CE(sat)}$	-	-	100	mV
Input Resistance	R1	3.3	4.7	6.1	K $\Omega$

## PNP Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified (TR2)

Parameter	Symbol	Min.	Typ.	Max.	Unit
DC Current Gain at $-V_{CE} = 5\text{ V}$ , $-I_C = 1\text{ mA}$	$h_{FE}$	200	-	-	-
Collector Base Cutoff Current at $-V_{CB} = 50\text{ V}$	$-I_{CBO}$	-	-	100	nA
Collector Emitter Cutoff Current at $-V_{CE} = 30\text{ V}$	$-I_{CEO}$	-	-	1	$\mu\text{A}$
Emitter Base Cutoff Current at $-V_{EB} = 5\text{ V}$	$-I_{EBO}$	-	-	100	nA
Collector Base Breakdown Voltage at $-I_C = 50\text{ }\mu\text{A}$	$-V_{(BR)CBO}$	50	-	-	V
Collector Emitter Breakdown Voltage at $-I_C = 1\text{ mA}$	$-V_{(BR)CEO}$	50	-	-	V
Emitter Base Breakdown Voltage at $-I_E = 50\text{ }\mu\text{A}$	$-V_{(BR)EBO}$	5	-	-	V
Collector Emitter Saturation Voltage at $-I_C = 5\text{ mA}$ , $-I_B = 0.25\text{ mA}$	$-V_{CE(sat)}$	-	-	100	mV
Input Resistance	R1	3.3	4.7	6.1	K $\Omega$



Electrical Characteristics Curves(TR1 NPN)

Fig 1. Base-Emitter Voltage vs. Collector Current

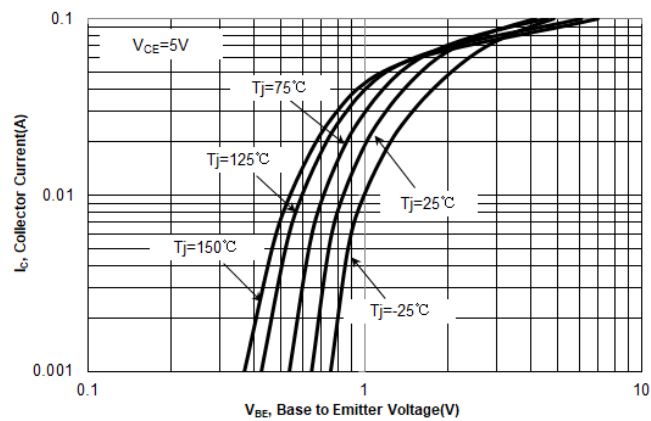


Fig 2. DC Current Gain vs. Collector Current

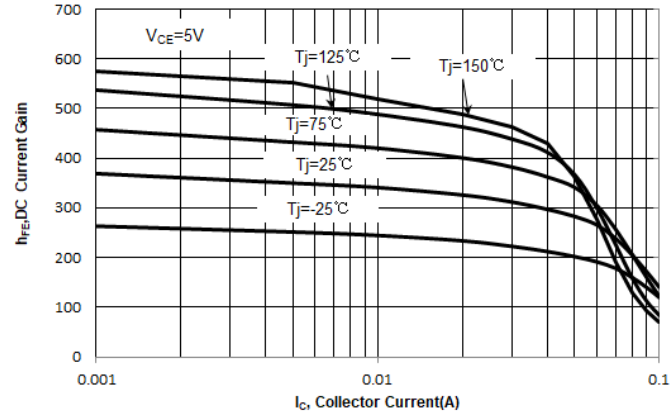
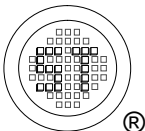
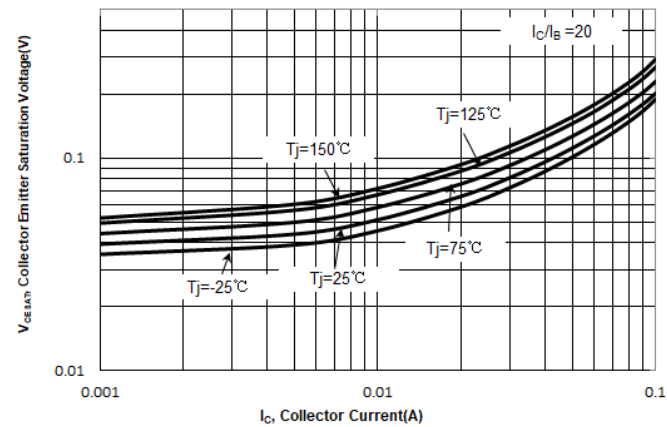


Fig 3.  $V_{CESAT}$  vs. Collector Current



Electrical Characteristics Curves(TR2 PNP)

Fig 1. Base-Emitter Voltage vs. Collector Current

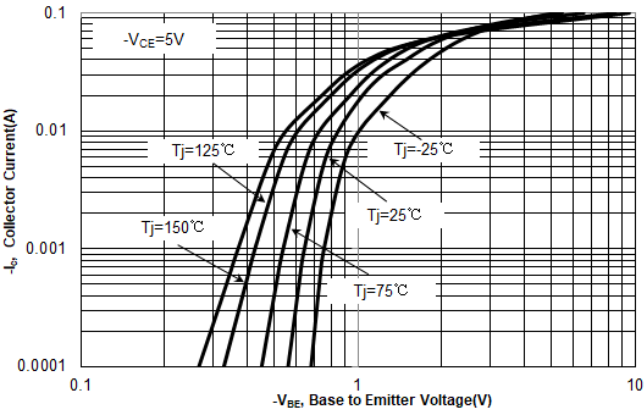


Fig 2. DC Current Gain vs. Collector Current

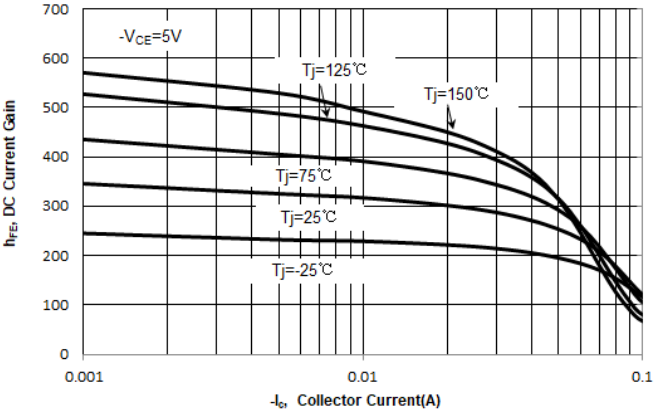
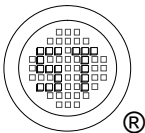
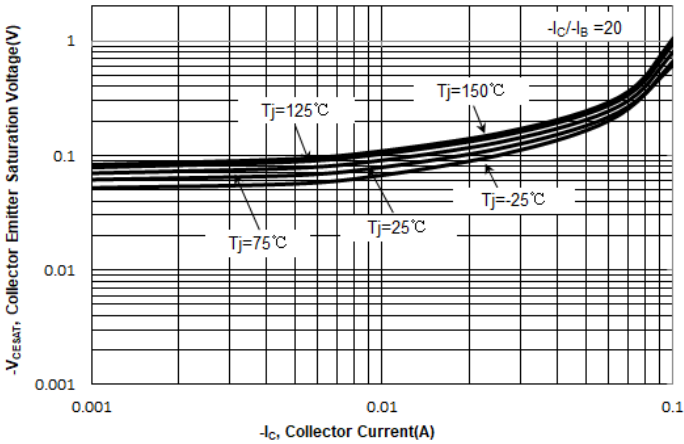


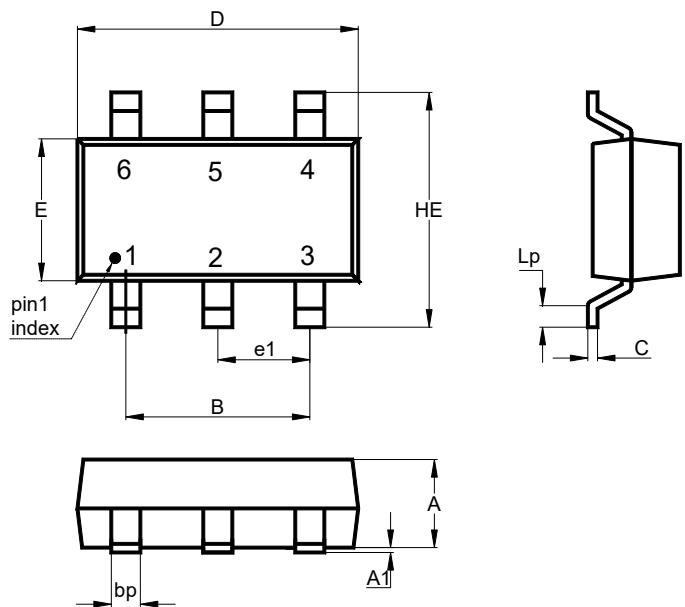
Fig 3.  $V_{CESAT}$  vs. Collector Current



# MMDTX430DW

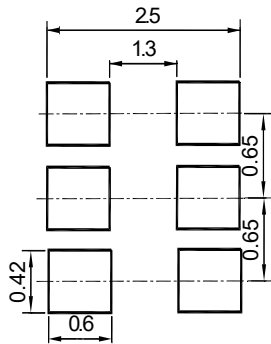
## Package Outline (Dimensions in mm)

SOT-363



Unit	A	A1	B	C	D	E	e1	HE	Lp	bp
mm	1.0 0.9	0.1 0	1.3 typ.	0.25 0.1	2.2 1.8	1.35 1.15	0.65 typ.	2.2 2.0	0.4 0.15	0.3 0.1

## Recommended Soldering Footprint



## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-363	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

## Marking information

"XK" = Part No.  
"YM" = Date Code Marking  
"Y" = Year  
"M" = Month  
Font type: Arial

